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NOTICE OF ALLOWANCE AND FEE(S) DUE

25096

7590

12/11/2002

PERKINS COIE LLP PATENT-SEA P.O. BOX 1247 SEATTLE, WA 98111-1247 EXAMINER

HO, TU TU V

ART UNIT CLASS-SUBCLASS

2818 257-200000

DATE MAILED: 12/11/2002

1	APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
•	09/944,246	08/30/2001	Setho Sing Fee	108298630US	1798

TITLE OF INVENTION: PACKAGED MICROELECTRONIC DEVICES AND METHODS OF FORMING SAME

APPLN. TYPE	SMALL ENTITY	· ISSUE FEE	PUBLICATION FEE	TOTAL FEE(S) DUE	DATE DUE
nonprovisional	NO	\$1280	\$300	\$1580	03/11/2003

THE APPLICATION IDENTIFIED ABOVE HAS BEEN EXAMINED AND IS ALLOWED FOR ISSUANCE AS A PATENT. PROSECUTION ON THE MERITS IS CLOSED. THIS NOTICE OF ALLOWANCE IS NOT A GRANT OF PATENT RIGHTS. THIS APPLICATION IS SUBJECT TO WITHDRAWAL FROM ISSUE AT THE INITIATIVE OF THE OFFICE OR UPON PETITION BY THE APPLICANT. SEE 37 CFR 1.313 AND MPEP 1308.

THE ISSUE FEE AND PUBLICATION FEE (IF REQUIRED) MUST BE PAID WITHIN THREE MONTHS FROM THE MAILING DATE OF THIS NOTICE OR THIS APPLICATION SHALL BE REGARDED AS ABANDONED. THIS STATUTORY PERIOD CANNOT BE EXTENDED. SEE 35 U.S.C. 151. THE ISSUE FEE DUE INDICATED ABOVE REFLECTS A CREDIT FOR ANY PREVIOUSLY PAID ISSUE FEE APPLIED IN THIS APPLICATION. THE PTOL-85B (OR AN EQUIVALENT) MUST BE RETURNED WITHIN THIS PERIOD EVEN IF NO FEE IS DUE OR THE APPLICATION WILL BE REGARDED AS ABANDONED.

HOW TO REPLY TO THIS NOTICE:

I. Review the SMALL ENTITY status shown above.

If the SMALL ENTITY is shown as YES, verify your current SMALL ENTITY status:

A. If the status is the same, pay the TOTAL FEE(S) DUE shown above

B. If the status is changed, pay the PUBLICATION FEE (if required) and twice the amount of the ISSUE FEE shown above and notify the United States Patent and Trademark Office of the change in status, or

If the SMALL ENTITY is shown as NO:

A. Pay TOTAL FEE(S) DUE shown above, or

B. If applicant claimed SMALL ENTITY status before, or is now claiming SMALL ENTITY status, check the box below and enclose the PUBLICATION FEE and 1/2 the ISSUE FEE shown above.

 Applicant claims SMALL ENTITY status. See 37 CFR 1.27.

II. PART B - FEE(S) TRANSMITTAL should be completed and returned to the United States Patent and Trademark Office (USPTO) with your ISSUE FEE and PUBLICATION FEE (if required). Even if the fee(s) have already been paid, Part B - Fee(s) Transmittal should be completed and returned. If you are charging the fee(s) to your deposit account, section "4b" of Part B - Fee(s) Transmittal should be completed and an extra copy of the form should be submitted.

III. All communications regarding this application must give the application number. Please direct all communications prior to issuance to Box ISSUE FEE unless advised to the contrary.

IMPORTANT REMINDER: Utility patents issuing on applications filed on or after Dec. 12, 1980 may require payment of maintenance fees. It is patentee's responsibility to ensure timely payment of maintenance fees when due.

PART B - FEE(S) TRANSMITTAL

Complete and send this form, together with applicable fee(s), to: Mail Box ISSUE FEE

Commissioner for Patents Washington, D.C. 20231

(703)746-4000

INSTRUCTIONS: This form should be used for transmitting the ISSUE FEE and PUBLICATION FEE (if required). Blocks 1 through 4 should be completed where appropriate. All further correspondence including the Patent, advance orders and notification of maintenance fees will be mailed to the current correspondence address as indicated unless corrected below or directed otherwise in Block 1, by (a) specifying a new correspondence address; and/or (b) indicating a separate "FEE ADDRESS" for

maintenance fee notifications CURRENT CORRESPONDENCE ADDRESS (Note: Legibly mark-up with any corrections or use Block 1) Note: A certificate of mailing can only be used for domestic mailings of the Fee(s) Transmittal. This certificate cannot be used for any other accompanying papers. Each additional paper, such as an assignment or 25096 12/11/2002 PERKINS COIE LLP formal drawing, must have its own certificate of mailing or transmission. PATENT-SEA Certificate of Mailing or Transmission I hereby certify that this Fee(s) Transmittal is being deposited with the United States Postal Service with sufficient postage for first class mail in an envelope addressed to the Box Issue Fee address above, or being facsimile transmitted to the USPTO, on the date indicated below. P.O. BOX 1247 SEATTLE, WA 98111-1247 (Depositor's name) (Signature (Date) APPLICATION NO. FILING DATE FIRST NAMED INVENTOR ATTORNEY DOCKET NO. CONFIRMATION NO. 09/944.246 08/30/2001 108298630US Setho Sing Fee 1798 TITLE OF INVENTION: PACKAGED MICROELECTRONIC DEVICES AND METHODS OF FORMING SAME APPLN. TYPE SMALL ENTITY ISSUE FEE PUBLICATION FEE TOTAL FEE(S) DUE DATE DUE nonprovisional NO \$1280 \$300 \$1580 03/11/2003 **EXAMINER** ART UNIT **CLASS-SUBCLASS** HO, TU TU V 2818 257-200000 1. Change of correspondence address or indication of "Fee Address" (37 CFR 1.363). 2. For printing on the patent front page, list (1) the names of up to 3 registered patent attorneys or agents OR, alternatively, (2) the name of a $\mbox{\ensuremath{\square}}$ Change of correspondence address (or Change of Correspondence Address form PTO/SB/122) attached. single firm (having as a member a registered attorney or agent) and the names of up to 2 ☐ "Fee Address" indication (or "Fee Address" Indication form PTO/SB/47; Rev 03-02 or more recent) attached. Use of a Customer Number is required. registered patent attorneys or agents. If no name is listed, no name will be printed. 3. ASSIGNEE NAME AND RESIDENCE DATA TO BE PRINTED ON THE PATENT (print or type) PLEASE NOTE: Unless an assignee is identified below, no assignee data will appear on the patent. Inclusion of assignee data is only appropriate when an assignment has been previously submitted to the USPTO or is being submitted under separate cover. Completion of this form is NOT a substitute for filing an assignment. (A) NAME OF ASSIGNEE (B) RESIDENCE: (CITY and STATE OR COUNTRY) Please check the appropriate assignee category or categories (will not be printed on the patent) ☐ individual ☐ corporation or other private group entity ☐ government 4a. The following fee(s) are enclosed: A check in the amount of the fee(s) is enclosed. ☐ Issue Fee Payment by credit card. Form PTO-2038 is attached. Publication Fee The Commissioner is hereby authorized by charge the required fee(s), or credit any overpayment, to Deposit Account Number ______(enclose an extra copy of this form). ☐ Advance Order - # of Copies Commissioner for Patents is requested to apply the Issue Fee and Publication Fee (if any) or to re-apply any previously paid issue fee to the application identified above. (Authorized Signature) (Date) NOTE; The Issue Fee and Publication Fee (if required) will not be accepted from anyone other than the applicant; a registered attorney or agent; or the assignee or other party in interest as shown by the records of the United States Patent and Trademark Office.

This collection of information is required by 37 CFR 1.311. The information is required to This collection of information is required by 37 CFR 1.311. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, Washington, D.C. 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, Washington, DC 20231.

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APPLICATION N	Ο.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/944,246 08/30/2001		08/30/2001	Setho Sing Fee	108298630US	1798
25096	7590	12/11/2002		EXAMIN	ER
PERKINS C)		HO, TU TU V	
PATENT-SEA P.O. BOX 1247			ART UNIT	PAPER NUMBER	
SEATTLE, WA 98111-1247				2818	
			DA	TE MAILED: 12/11/2002	

Determination of Patent Term Adjustment under 35 U.S.C. 154 (b) (application filed on or after May 29, 2000)

The patent term adjustment to date is 0 days. If the issue fee is paid on the date that is three months after the mailing date of this notice and the patent issues on the Tuesday before the date that is 28 weeks (six and a half months) after the mailing date of this notice, the term adjustment will be 0 days.

If a continued prosecution application (CPA) was filed in the above-identified application, the filing date that determines patent term adjustment is the filing date of the most recent CPA.

Applicant will be able to obtain more detailed information by accessing the Patent Application Information Retrieval (PAIR) system. (http://pair.uspto.gov)

Any questions regarding the patent term extension or adjustment determination should be directed to the Office of Patent Legal Administration at (703)305-1383.



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APPLICATION NO. FILING DATE		ILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/944,246 08/30		08/30/2001	Setho Sing Fee	108298630US 1798		
25096	7590	12/11/2002		EXAMINER		
PERKINS COIE LLP				HO, TU TU V		
PATENT-SEA P.O. BOX 1247				ART UNIT	PAPER NUMBER	
SEATTLE, WA 98111-1247 UNITED STATES				2818 DATE MAILED: 12/11/2002		

Notice of Fee Increase on January 1, 2003

If a reply to a "Notice of Allowance and Fee(s) Due" is filed in the Office on or after January 1, 2003, then the amount due will be higher than that set forth in the "Notice of Allowance and Fee(s) Due" since there will be an increase in fees effective on January 1, 2003. See Revision of Patent and Trademark Fees for Fiscal Year 2003; Final Rule, 67 Fed. Reg. 70847, 70849 (November 27, 2002).

The current fee schedule is accessible from: http://www.uspto.gov/main/howtofees.htm.

If the issue fee paid is the amount shown on the "Notice of Allowance and Fee(s) Due," but not the correct amount in view of the fee increase, a "Notice to Pay Balance of Issue Fee" will be mailed to applicant. In order to avoid processing delays associated with mailing of a "Notice to Pay Balance of Issue Fee," if the response to the Notice of Allowance and Fee(s) due form is to be filed on or after January 1, 2003 (or mailed with a certificate of mailing on or after January 1, 2003), the issue fee paid should be the fee that is required at the time the fee is paid. If the issue fee was previously paid, and the response to the "Notice of Allowance and Fee(s) Due" includes a request to apply a previously-paid issue fee to the issue fee now due, then the difference between the issue fee amount at the time the response is filed and the previously paid issue fee should be paid. See Manual of Patent Examining Procedure, Section 1308.01 (Eighth Edition, August 2001).

Questions relating to issue and publication fee payments should be directed to the Customer Service Center of the Office of Patent Publication at (703) 305-8283.

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` •	Application No.	Applicant(s)	
Notice of Allowability	09/944,246	FEE ET AL.	
House of Allowability	Examiner	Art Unit	
	Tu-Tu Ho	2818	
The MAILING DATE of this communication appear All claims being allowable, PROSECUTION ON THE MERITS IS herewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RI of the Office or upon petition by the applicant. See 37 CFR 1.313 1. This communication is responsive to Applicant's Amendment of the allowed claim(s) is/are 1-9,11-23,32-35,39 and 40. 3. The drawings filed on are accepted by the Examine decknowledgment is made of a claim for foreign priority und a) All b) Some* c) None of the: 1. Certified copies of the priority documents have	ears on the cover sheet with the co (OR REMAINS) CLOSED in this app or other appropriate communication GHTS. This application is subject to and MPEP 1308. ent filed 04 November 2002.	orrespondence address blication. If not included will be mailed in due course. THI b withdrawal from issue at the initia	S ative
Certified copies of the priority documents have			
3. Copies of the certified copies of the priority doc International Bureau (PCT Rule 17.2(a)). * Certified copies not received: 5. Acknowledgment is made of a claim for domestic priority un (a) The translation of the foreign language provisional age 6. Acknowledgment is made of a claim for domestic priority un	der 35 U.S.C. § 119(e) (to a provision		,
Applicant has THREE MONTHS FROM THE "MAILING DATE" of	this communication to file a reply co	mplying with the requirements not	ed
below. Failure to timely comply will result in ABANDONMENT of t	his application. THIS THREE-MON	TH PERIOD IS NOT EXTENDAB	LE.
7. A SUBSTITUTE OATH OR DECLARATION must be submit INFORMAL PATENT APPLICATION (PTO-152) which gives reason	tted. Note the attached EXAMINER' on(s) why the oath or declaration is d	S AMENDMENT or NOTICE OF leficient.	
8. ☑ CORRECTED DRAWINGS must be submitted. (a) ☐ including changes required by the Notice of Draftspers. 1) ☐ hereto or 2) ☐ to Paper No			
(b) ☑ including changes required by the proposed drawing or Examiner.			
(c) including changes required by the attached Examiner's	Amendment / Comment or in the Or	ffice action of Paper No	
Identifying indicia such as the application number (see 37 CFR 1.8 of each sheet. The drawings should be filed as a separate paper v	4(c)) should be written on the drawing vith a transmittal letter addressed to the	gs in the top margin (not the back) ne Official Draftsperson.	
 DEPOSIT OF and/or INFORMATION about the deposit attached Examiner's comment regarding REQUIREMENT FOR TH 	t of BIOLOGICAL MATERIAL m E DEPOSIT OF BIOLOGICAL MATI	ust be submitted. Note the ERIAL.	
Attachment(s)		•	
Notice of References Cited (PTO-892) Notice of Draftperson's Patent Drawing Review (PTO-948) Important Disclosure Statements (PTO-1449), Paper No Examiner's Comment Regarding Requirement for Deposit of Biological Material	4☐ Interview Summar — 6☑ Examiner's Amend	Patent Application (PTO-152) y (PTO-413), Paper No dment/Comment nent of Reasons for Allowance	

Application/Control Number: 09/944,246

Art Unit: 2818

#15/C

DETAILED ACTION

1. Applicant's Amendment filed 04 November 2002 has been reviewed and placed of record in the file.

- 2. The Declaration filed on 04 November 2002 under 37 CFR 1.131 is sufficient to overcome the Huang's reference (U.S. Patent Application Publication US 2002/0027273).
- 3. A certified copy of priority document has been received and has been placed of record in the file.

Examiner's Amendment

- 4. An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.
- 5. Claim 10 belongs to Invention Group "b", Embodiment of Figures 10A-D and 11, non-elected without traverse. Accordingly, claim 10 has been cancelled.

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6. Newly submitted claims 41 and 42 directed to an invention that is independent or distinct from the invention originally claimed for the following reasons: Claims 41 and 42 recites: "releasably attaching a back surface of a microelectronic device to a surface of a support; thereafter, releasably attaching a lead frame to the support, the lead frame having a thickness and having an opening passing through the thickness" wherein the limitation "thereafter" is distinct from the elected invention.

Since applicant has received an action on the merits for the originally presented invention, this invention has been constructively elected by original presentation for prosecution on the merits. Accordingly, claims 41 and 42 are withdrawn from consideration as being directed to a non-elected invention and have been cancelled. See 37 CFR 1.142(b) and MPEP § 821.03.

7. In claim 12, "L-shapedlead fingers" has been changed to "L-shaped lead fingers".

Allowable Subject Matter

8. Claims 1-9, 11, 39-40, 12-23, and 32-35 (to be renumbered 1-18) are allowable over the prior art of record.

The following is an examiner's statement of reasons for allowance: The prior art of record fails to teach or render obvious a method of assembling a stacked microelectronic device assembly and the resulting device having all exclusive limitations as recited in claims 1, 12, and

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32, including a lead frame, a microelectronic device, a releasable support, and an encapsulant, characterized in that:

the encapsulant is defined by the releasable support, the microelectronic device, and the lead frame;

an upper surface of the encapsulant is aligned with the upper surface of the lead frame; and that either:

for the stacked configuration, an electrical insulator covers a front surface of the lead fingers of the top lead frame and that a gap is defined between the two microelectronic devices; or:

L-shaped lead fingers as defined in claim 12.

Note that although not explicitly disclosed, the limitation: "an upper surface of the encapsulant is aligned with the upper surface of the lead frame" is inherent in the invention as claimed in claims 1, 12, or 32 ("filling the opening..." and "removing excess encapsulant deposited on front surfaces of any of the lead fingers" among other steps (claim 12) and for the stacked configuration (claim 1 or claim 32), the limitation is obvious: one can not electrically couple the two microelectronic device assemblies as disclosed if an upper surface of the encapsulant is not aligned with the upper surface of the lead frame. Similar note is made for the limitation "a gap is defined between the two microelectronic devices".

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue

fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion

9. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tu-Tu Ho whose telephone number is (703) 305-0086. The examiner can normally be reached on 6:30 am - 5:00 pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, DAVID NELMS can be reached on (703) 308-4910. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 308-7722 for regular communications and (703) 308-7722 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-1782.

Tu-Tu Ho November 03, 2002 David Nelms
Supervisory Patent Examiner
Technology Center 2800

1'

stacked package, method:
attach leadframe and chip to support
cavity for resin defined by leadframe
back surface of chip exposed
gap between chips
cover leads of the top chip

```
2'
3'
4
5
6'
7
8
9
HO lower surfaces of lead fingers staggered
11 10
39 11
40 12
```

micro device, method
attach support to chip and leadframe
back surface of chip exposed
L-shaped lead fingers: back surface larger front surface
(removing excess resin)

13' (Y
14' (5)
16' 17
17' (8) second package
stacked 2nd to 1st chip package
18 19
19 20
20 21
21 22
22 28
23 24

stacked package:
gap between chips though not explicitly
back surface of chip exposed
Electrical contacts between chips
cover leads of the top chip
33 24 gap between chips
34 44

35 VS

micro device, method attach chip then leadframe to support cavity for resin defined by leadframe back surface of chip exposed 42'